

Title (en)  
ROTARY APPLICATOR HEAD

Title (de)  
ROTATIONS-AUFTRAGSKOPF

Title (fr)  
TETE D'APPLICATION ROTATIVE

Publication  
**EP 1042074 A1 20001011 (DE)**

Application  
**EP 98966344 A 19981216**

Priority  
• DE 19757238 A 19971222  
• DE 19757237 A 19971222  
• EP 9808246 W 19981216

Abstract (en)  
[origin: US6464785B1] An application head (11) for contract-free application of hot-melt adhesive onto a width of material (22) has a housing (12) with a control slide chamber (20). A cylinder control slide (13) is supported and is rotatably drivable in the housing. At least one supply aperture introduces an adhesive into the control slide chamber (20). A slotted nozzle (18) releases the adhesive. The slotted nozzle is controllable by the cylinder control slide (13). The nozzle extends transversely to the direction of movement of the width of material (22). The cylinder control slide (13) has a cylindrical surface which is able to seal the slotted nozzle (18) from the inside. The control slide (13) also has surface grooves (17) in the cylindrical surface. The grooves, as a function of their rotational positions, are able to communicate with the slotted nozzle. Furthermore, the cylinder control slide (13) inside the control slide chamber, has either an inner cavity (29) supplied with medium through a supply aperture, as well as radial exit bores (28) leading from the inner cavity into the surface grooves, or it has a helical or spiral-shaped surface groove in the cylindrical surface, as well as a storage volume for medium, which communicates with the at least one surface groove.

IPC 1-7  
**B05C 5/02**; **B05C 1/10**

IPC 8 full level  
**B05B 1/14** (2006.01); **B05C 1/10** (2006.01); **B05C 5/00** (2006.01); **B05C 5/02** (2006.01); **B05C 11/10** (2006.01)

CPC (source: EP US)  
**B05C 1/10** (2013.01 - US); **B05C 5/0258** (2013.01 - EP US); **B05C 5/0275** (2013.01 - EP US); **B05C 11/1026** (2013.01 - EP US);  
**B05C 5/0233** (2013.01 - EP US)

Citation (search report)  
See references of WO 9932233A1

Designated contracting state (EPC)  
CH ES FR GB IT LI NL SE

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**US 6464785 B1 20021015**; EP 1042074 A1 20001011; EP 1042074 B1 20030402; JP 2001526114 A 20011218; JP 3504921 B2 20040308;  
US 2003000464 A1 20030102; US 6827777 B2 20041207; WO 9932233 A1 19990701

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**US 58242100 A 20000816**; EP 9808246 W 19981216; EP 98966344 A 19981216; JP 2000525213 A 19981216; US 20833402 A 20020730